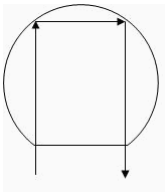
Part Number	Customer

Category		Parameter	Specification	Measurement Method
OverallWafer	1.0	Diameter	150.00 +/- 0.30 mm	
	2.0	Primary Flat Orientation	{110}+/-1 degree	Wafer Vendor
	3.0	Primary Flat Length	47.50 +/- 2.50 mm	Wafer Vendor
	4.0	Secondary Flat Orientation	None	
	5.0	Overall Thickness	637.00 +/- 7.00 µm	ADE, 100%
	6.0	Total Thickness Variation (TTV)	<5.00µm	Guaranteed by Process
	7.0	Bow	<80.00µm	ADE to ASTM F534, 20%
	8.0	Warp	<80.00µm	ADE to ASTM F657, 20%
	9.0	Edge Chips	0	Bright Light, 100% (note 2)
	10.0	Edge Exclusion	7mm	
HandleSilicon	11.0	Handle Growth Method	CZ	Wafer Vendor
	12.0	Handle Orientation	{100} +/- 1 degree	Wafer Vendor
	13.0	Handle Thickness	575.00 +/- 5.00 µm	ADE, 100%
	14.0	Handle Doping Type	N	Wafer Vendor
	15.0	Handle Dopant	Phosphorous	Wafer Vendor
	16.0	Handle Resistivity	1 - 10 Ohmcm	Wafer Vendor
	17.0	Backside Finish	Lapped and Etched	Wafer Vendor
BuriedOxide	18.0	Oxide Type	Thermal	
	19.0	Oxide Thickness	20,000.00 +/- 1,000.00 A	Nanospec centre point, 4%
	20.0	Oxide formed on	Device Wafer	
DeviceSilicon	21.0	Device Growth Method	FZ or low Oi CZ	Wafer Vendor
	22.0	Oxygen Concentration	<7E17 cm-3	Wafer Vendor
	23.0	Carbon Concentration	<2E16 cm-3	Wafer Vendor
	24.0	Device Orientation	{100} +/- 1 degree	Wafer Vendor
	25.0	Nominal Thickness	57.00 +/- 2.00 µm	FTIR, 100% 9-Pt (note3)
	26.0	Distance to device silicon edge from wafer edge	< 5mm	Wafer Vendor
	28.0	Device Doping Type	N	Wafer Vendor
	29.0	Device Dopant	Phosphorous	Wafer Vendor
	30.0	Device Resistivity	1.0 - 3.0 Ohm-cm	Wafer Vendor
	34.0	Voids	0	Bright Light, 100% (note2)
	35.0	Scratches	none	Bright Light, 100% (note2)
	36.0	Haze	none	Bright Light, 100% (note2)

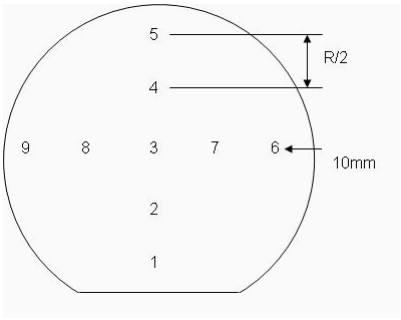
Part Number	Customer

Category	Parameter	Specification	Measurement Method
Shipping Details	Wafer per box :	Max 25	
	Packaging :	Taped Polypropylene Wafer Box Empak, Ultrapak, 150.00mm Antistatic Double Bagging	
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness	
Explanatory Notes	1. Microscope inspection performed using microscope scan as below. 5x objective.		



2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.

3. 9 point measurement are as shown in the diagram below:



Additional Information